

Applicant: Wang
Application Serial No.: 10/736,486
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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of the claims in the application:

List of Claims:

- 1) (Currently Amended) A method of packaging a high-density integrated circuit with at least one microchip disposed on a substrate having a plurality of terminal pads provided thereon, said method comprising:
 - a) providing pre-insulated bond wires;
 - b) forming an array of coated bonding pads on said microchip; and
 - c) directly connecting any of said terminal pads to any of said coated bonding pads by attaching said pre-insulated bond wires ~~directly onto~~ between any of said bonding pads and ~~directly onto~~ any of said terminal pads disposed on said substrate.
- 2) (Original) The method of packaging a high density integrated circuit according to claim 1, wherein said bonding pads are located at selected locations on said microchip.
- 3) (Original) The method of packaging a high density integrated circuit according to claim 2, wherein said bonding pads comprise a metallized aluminium, gold, or copper material.
- 4) (Currently Amended) The method of packaging a high density integrated circuit according to claim 1, wherein said pre-insulated bond wires are selected from a group consisting of gold, ~~aluminum~~ aluminium, copper and combinations thereof.

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- 5) (Original) The method of packaging a high density integrated circuit according to claim 1, wherein said pre-insulated bond wires are attached onto said bonding pads by a ball shaped joint.
- 6) (Original) The method of packaging a high density integrated circuit according to claim 1, wherein a plurality of microchips are disposed on said substrate and said bonding pads are located on the microchips.
- 7) (Original) The method of packaging a high density integrated circuit according to claim 6, including attaching said pre-insulated bond wires to said bonding pads to thereby connect adjacent microchips.
- 8) (Currently Amended) A method of packaging a high density integrated circuit having at least one semiconductor microchip disposed on a substrate having a plurality of terminal pads provided thereon, said method comprising;
 - a) providing pre-insulated bond wires;
 - b) forming a plurality of bonding pads in a plurality of rows and columns over a surface of said microchip; and
 - c) connecting ~~selected~~ any of said bonding pads on said microchip with ~~selected~~ any of said terminal pads on said substrate with said pre-insulated bond wires.
- 9) (Original) The method of packaging a high density integrated circuit according to claim 8, including coating the integrated circuit with a protective encapsulating material.

- 10) (Original) The method of packaging a high density integrated circuit according to claim 8, wherein said bonding pads are located at selected locations over the entire surface of said microchip.
- 11) (Original) The method of packaging a high density integrated circuit according to claim 8, wherein a plurality of semiconductor microchips are disposed on said substrate, and interconnections among selected bonding pads on said microchips are provided by pre-insulated bond wires bonded to said selected bonding pads.
- 12) (Original) The method of packaging a high density integrated circuit according to claim 11, wherein said pre-insulated bond wires are selected from a group consisting of gold, aluminium, copper and combinations thereof.
- 13) (Currently Amended) An integrated circuit package comprising:
 - a) a substrate having terminal pads arranged in at least one row along a perimeter of a surface of said substrate;
 - (b) ~~vias~~ electrically conductive via holes connecting said terminal pads directly to connectors on an opposite side of said substrate;
 - (c) a semiconductor chip mounted on the substrate, inside said perimeter, said chip having bond pads located on a surface of said chip; and
 - (d) a plurality of insulated bond wires, each of said bond wires extending from a bond pad on said chip to a terminal pad on said substrate, said substrate being sized and shaped to provide a sufficient number of rows of terminal pads and associated ~~vias~~ said via holes so that horizontal traces through said substrate are not required.

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- 14) (Original) An integrated circuit package as claimed in claim 13, wherein said substrate is configured to contain a minimal number of layers, to reduce interlayer inductance, capacitance, and cross talk, and to increase the range of bandwidth performance.
- 15) (Original) An integrated circuit package as claimed in claim 14, wherein said substrate is a single layer substrate.
- 16) (Original) An integrated circuit package as claimed in claim 14, wherein said substrate contains no lead frames.
- 17) (Original) An integrated circuit package as claimed in claim 16, wherein said opposite side of said substrate contains a ball grid array, and each of said terminal pads connects to a ball in said ball grid array through said via directly traversing said substrate.
- 18) (Original) An integrated circuit package as claimed in claim 13, wherein said insulated bond wires extending between said bond pads on said chip and said terminal pads on said substrate are positioned to reduce parallelism between adjacent wires, to in turn reduce cross talk and increase the range of bandwidth performance.
- 19) (Original) An integrated circuit package as claimed in claim 18, wherein said insulated bond wires are attached in a generally X or Y shaped pattern.
- 20) (Original) An integrated circuit package as claimed in claim 19, wherein said generally X or Y shaped pattern is an in line or staggered X-Y grid pattern.

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- 21) (Original) An integrated circuit package as claimed in claim 13, wherein at least one of said bond pads is located in an interior portion of said surface of said chip.
- 22) (Original) An integrated circuit package as claimed in claim 21, wherein said bond pad located in said interior portion is electrically connected to one of a power connection and a ground connection on said chip.
- 23) (Currently Amended) A method of manufacturing an integrated circuit package, said method comprising:
- a) providing a semiconductor chip having bond pads located on a surface of said chip, at least a portion of said bond pads being designated to provide input/output functions;
 - b) providing a substrate having terminal pads arranged in at least one row along a perimeter of a surface of said substrate, said substrate having ~~vias~~ electrically conductive via holes connecting said terminal pads directly to connectors on an opposite side of said substrate, said substrate being sized and shaped to contain a sufficient number of rows of terminal pads and associated ~~vias~~ said via holes so that horizontal traces through said substrate are not required;
 - c) mounting said semiconductor chip on said surface of said substrate, inside said perimeter; and
 - d) connecting insulated bond wires between said portion of said bond pads and said terminal pads.
- 24) (Original) A method of manufacturing as claimed in claim 23, wherein said step of connecting insulated bond wires in step (d) comprises positioning said bond wires to reduce parallelism between adjacent wires, to in turn reduce cross talk and increase the range of bandwidth performance.

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25) (Original) A method of manufacturing as claimed in claim 23, wherein said connectors on said opposite side of said substrate are balls in a ball grid array.